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C A L E N D A R O F E V E N T S

For reservations call the IEEE office at 236-4609

(unless otherwise indicated)

COPY DEADLINE: NO LATER THAN THE 25th OF THE MONTH

MAY	5	Tour - CTA Power Distn. & Systems Control Facili.	Industry Appls./ Industrial Elec- tronics Soc.	Merchandise Mart Chicago	Begin. 5:00 PM Meet at Center Lobby
	5	MAC '84 (Midwest Acoustics Conf.) "Cinema Sound"	Audio Engrng. Soc., Chgo. Acous. & Audio CRC of ASA & IEEE	Film Ctr., School of Art Inst. of Chicago Columbus Dr./Jackson	9:00 AM--4:00 PM (Inf. Tom Yackish 219:844-0520 x471)
	9	"Radio Astronomy"	Power Engrng. Soc.	Carson Pirie Scott Wabash & Monroe Sts. Highland Rm., 8th Fl.	Social 11:30 AM Lunch 12:00 PM Meeting 12:30 PM
	14	"Mini Microwave Expo"	Antennas & Prop./ Microwave Theory & Techniques Soc.	Arlington Park Hilton Rt.53 & Euclid Ave. Arlington Heights	Exhpts. 3:30-6:30 Dinner 6:30-PM Meeting 7:30 PM
	15	Monthly Meeting - ALL WELCOME	IEEE Executive Cte.	McDonald's Plaza NE corner McDonald Dr. at 22nd, Oak Brook	Meeting 7:30 PM
	19	Plant Facili.Tour/ Picnic	Fox Valley Sub.	Great America Gurnee, Illinois	(See article in this issue)
	19	Tour-Pwr.Test Lab., McGraw-Edison Pwr. Systems Group	Power Engrng. Soc.	Franksville, Wisconsin	10:00 AM-12:00 PM
	30	"New Directions in Vehicle Electronics"	Fox Valley Sub.	Wilton Manor 2200 N. Main St. at Geneva Rd., Wheaton	Social 6:00 PM Dinner 7:00 PM Meeting 8:00 PM
JUNE	11	"Low Sidelobe Phased Array Antennas"	Antennas & Prop./ Microwave Theory & Techniques Soc.	Louis' Restaurant 351 E. Lake St. Addison	Social 5:30 PM Dinner 6:30 PM Meeting 7:30 PM
	12	Monthly Meeting - ALL WELCOME	IEEE Executive Cte.	McDonald's Plaza NE corner McDonald Dr. at 22nd, Oak Brook	Meeting 7:30 PM

CHICAGO SECTION ELECTS OFFICERS AND EXECUTIVE COMMITTEE - The Chicago Section of the IEEE has elected their officers and members of the Executive Committee for the 1984-85 term. Voting was by ballot printed in the April Scanfax.

Officers elected are: *Chairman* - George Thomas, Contemporary Control Systems Inc.; *Vice Chairman* - Henry Korman, Noble U.S.A.; *Treasurer* - Norbert Orszula, Brown & Root, Inc.; *Secretary* - Margaret Jones, Bell Telephone Laboratories. Members of the Executive Committee elected by mail ballot are: Andy Gasiorowski, Allen-Bradley Company; Keith Klontz, McHenry Electric & Supply Company; Douglas Smith, Square D Company; George Stout, G.P.E. Controls; Terence Sumner, Motorola, Inc.; John Tyner, Cleworth Publications; John Waters, Bussmann Manufacturing Division; Howard Wolfman, Grayhill, Inc. The Executive Committee also includes the chairmen of both the Fox Valley and Northwest Subsections and the chairmen of each of the active group or society chapters. According to the Chicago Section Bylaws, they are automatically members of the Executive Committee and do not have to be voted upon by the membership.

IAS TO TOUR CTA FACILITIES - The Industry Applications/Industrial Electronics Societies will tour the CTA Communications and Power Control Center on May 5, 1984. Areas to be toured are the Bus, Rail and Power Control Center. Highlights include two-way radio communication with vehicles, the silent alarm system, electro-mechanical rail schedule monitoring and weather monitoring. Reservations required. The 45-minute tour is scheduled for 5:00 P.M. If necessary, a second tour will start at 5:45 P.M.

"MINI MICROWAVE EXPO" - The latest developments in microwave instrumentation and components will be displayed and discussed during the afternoon and evening presentation on May 14, 1984. The afternoon portion, a microwave "mini trade show" will be followed by a free roast beef dinner hosted by the Chicago area microwave manufacturers and manufacturers' representatives. After dinner, there will be a series of short technical presentations on selected new microwave products. The "expo" will be sponsored by the Chicago Chapter, Microwave Theory & Techniques/Antennas & Propagation Societies. Reservations are required.

MAC '84 - "Cinema Sound" will be the subject of MAC '84 a one day program featured by the Midwest Acoustics Conference in conjunction with the School of the Art Institute of Chicago on May 5, 1984 in their Film Center. Highlighting the program will be a presentation by Tomlinson Holman, Chief Engineer of Lucasfilm, Ltd. who will have film clips from hit releases Star Wars, The Empire Strikes Back and Raiders of the Lost Ark. Using these film clips, as well as original unreleased clips from the same movies, he will demonstrate the contrasts between original and final audio versions of these movies

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as well as behind the scenes to see the kind of creative choices that go into putting sound on film and to experience innovative audio techniques. Cinemascope visual presentations of the program will be complemented by a 6 channel multi speaker sound system using Dolby noise reduction specially installed for MAC '84.

FOX VALLEY TO TOUR PLANT FACILITIES AT GREAT AMERICA - The Fox Valley Subsection will have a tour/picnic at Great America on May 19, 1984. The picnic area will be the meeting place at 10:00 A.M. (park opens at 9:00 A.M.). Four groups of 25 each will tour the plant facilities. Lunch will be from 12 noon to 1:30 P.M. in the picnic area and includes hamburgers, hot dogs, various salads and free cola - extra charge for beer. Entrance fee/lunch cost will be \$17 per person. Checks must be mailed **in advance** to Neal Keating, Allen-Bradley Company, 838 S. Desplaines Street, Chicago 60607, (922-9302) and made payable to IEEE Fox Valley Subsection. The park is open all day. Only the first 100 reservations will be accepted.

Professional Activity

UPDATE

ENGINEERING ACADEMY STUDY URGES STEPS TO BOLSTER NATION'S ELECTRONICS INDUSTRY - U.S. Leadership in the electronics industry is in danger of being eroded during the next decade by competition from eastern Asia and western Europe because of high capital costs, technical personnel shortages and trade barriers according to a National Academy of Engineering (NAE) study released February 10. To meet this challenge, the report says the U.S. must formulate an industrial policy that will enable its electronics firms to compete vigorously in world markets. "The U.S. Government, working with industry and the universities, must develop a statement of national goals for the electronics industry," the report says. "This nation has traditionally had an aversion to any effort associated with national planning, particularly if it is to be done by the government. Yet other nations are, within their systems, clearly planning and marshalling major resources to enhance the long-term international competitiveness of their industries."

A program to enhance the competitiveness of the U.S. electronics industry requires major policy initiatives in R&D, capital formation, education and training, international trade and monetary reforms, the report says. The costs and benefits of policies in each area must be debated in an open public forum in order to achieve a broad-based consensus involving the industry, government and universities, the report adds. The NAE report on the electronics industry is the fifth of a series of seven designed to identify global shifts of industrial technology capacity on a sector-by-sector basis, relate those shifts to technological and other factors and assess prospects for further technological change and industrial development.

Just as the NAE report was issued, a House subcommittee approved (on February 8) a bill that calls on the U.S. to develop a country-wide industrial policy. The legislation (H.R. 4360), which was sponsored by Rep. John LaFaive (D., N.Y.) was approved on a party-line vote of 13-9. It creates two new agencies: a council to investigate the competitiveness of American companies, and a bank to make loans and loan guarantees and purchase stock in companies without capital to modernize to meet foreign competition. The bill must now go to the parent committee on Banking and Currency for consideration.

IEEE CHICAGO SECTION PLACEMENT SERVICE - The Chicago Section is now offering a Placement Service for its members free of charge. The program is intended for those who are Member Grade and above, and is a positive step to help our members who are unemployed. If interested in any of the applicants listed below, call the IEEE office (236-4609) for their name and phone number. If marked "confidential," the applicant will be contacted by the IEEE office so that he/she may contact the prospective employer.

AF - Electromagnetic, telecommunications systems engineering analysis, design
AG - AA programmer software engineer seeking entry level position
AH - Situ. wanted (AF group) M.E. with 5 yrs. teaching and industrial experience
AI - Principal Electrical Engineer - generating station and substation projects
AJ - Technologist specializing in digital development
AK - Electl.drafting-field changes,updating cable tabs.,revis.& updating master diagrams

If you are an IEEE member and unemployed, call or write the Electric Association for the necessary form. Direct your request to: IEEE Placement Service • c/o Electric Association • 125 S. Clark Street - Room 1545 • Chicago, Illinois 60603.

The IEEE and Electric Association waive any responsibility in determining the credibility, accuracy or qualifications of applicants or employers.

AN ADVISORY FROM THE COMPTON GROUP: HOW TO TELL IF IT'S TIME TO MOVE OUT— AND BE EXCITED AGAIN

- | | |
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| ☐ Your contributions go unrecognized. | ☐ You spend more time "putting out fires" than in finding innovative solutions. |
| ☐ Professional development is not encouraged. | ☐ Your environment lacks professionalism. |
| ☐ There is no discernible management plan for your future growth. | ☐ Your input is less frequently sought. You're becoming "lost in the crowd." |
| ☐ Your company has become more a follower than a leader. | ☐ Internal politics intrude upon your work and the organization's functioning. |
| ☐ You feel you have "been there before" in facing a new project. | ☐ Every workday seems interminable, leaving you without enthusiasm, zest and cheer. |
| ☐ Your support staff is unqualified or insufficient, forcing too many details on your shoulders. | ☐ You feel your work—and possibly your personal life—is suffering. |

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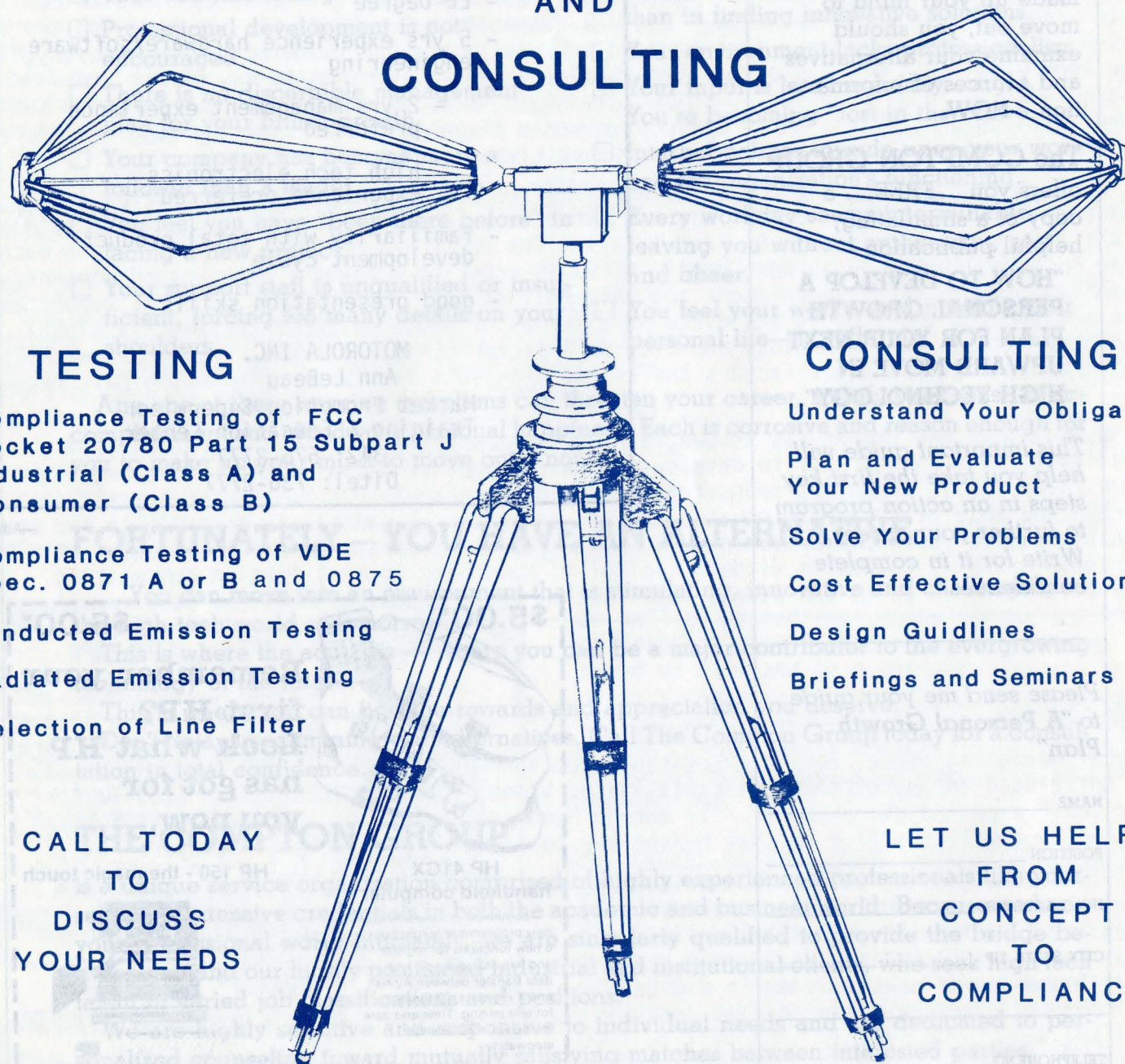
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